

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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# Field-Proven, Interoperable, and Standards-Compliant Portfolio





## **PCI Express Solutions**

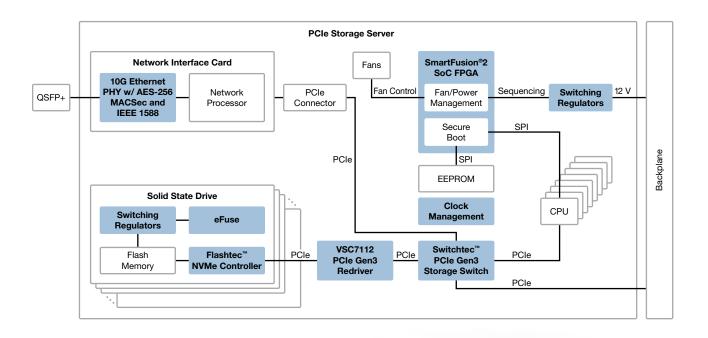
PCI Express (PCIe) is a widely deployed bus interconnect interface that is commonly used in server platforms. Increasingly, it is also used as a storage and GPU interconnect solution. PCIe Gen3 supports 8 GT/s of throughput per PCIe lane, and Gen4 supports 16 GT/s. Typical implementations utilize ×2, ×4, ×8, and ×16 lane width interconnect configurations—directly from the host root complex or through PCIe switches to endpoint PCIe devices.

Microsemi is a leader in PCle, having introduced multiple industry firsts. Highlights include:

- PCIe Gen3 SAS/SATA RAID controller
- The industry's highest density and lowest power Gen3 PCle Switches, Switchtec PSX and PFX

- PCle Gen3 NVMe Flash controller (Flashtec<sup>™</sup>), followed by a second-generation introduction of the industry's fastest PCle Gen3 NVMe SSD controllers
- PCle Gen3 redriver with EQNOX™ adaptive equalization
- Flash-based FPGAs and SoCs used in CPLD functions with integrated PCle endpoint implementations

Microsemi offers a flexible product portfolio to intelligently design your PCle system for data center, communications, defense, and industrial applications. Our industry-leading PCle solutions include storage and fanout switches, NVMe controllers, NVRAM drives, redrivers, and timing solutions, and flash-based FPGAs and SoCs.







### **PCI Express Solutions**

### Microsemi Advantages

### Switchtec<sup>™</sup> PCIe Switches

- Options from 24 to 96 lanes
- Industry's most flexible port bifurcation, from ×2 to ×16 lanes per port
- Highest port and non-transparent bridge (NTB) density, with up to 48 ports and 48 NTBs
- Highest switch partition density
- Industry's first integrated programmable processor
- Industry's first integrated enclosure management solution
- PFX-I supports industrial temperature ranges, -40 °C ( $T_A$ ) to 105 °C ( $T_A$ )

### Flashtec™ NVMe Controllers

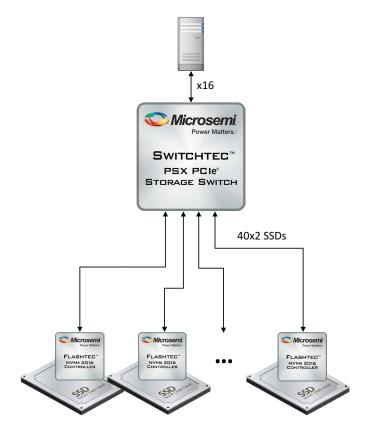
- World's first and fastest enterprise PCle NVMe controller, with up to 850K IOPS and up to 8 TB
- Software-defined flash: flexible, programmable architecture optimized for cost, performance, and endurance
- Enterprise-class reliability, availability, and serviceability with NVMe management features and industry's only dual-port controller

#### Flashtec NVRAM Drives

- Non-volatile DRAM with over 10 million IOPS, sub-microsecond latency
- Industry-standard interfaces that are application-friendly for ease of integration
- Zero-maintenance green backup
- Unlimited endurance NVRAM
- Small form factor for high-density rack solutions

### **Signal Integrity**

- PCle Gen 3.0 solutions supporting ×1 to ×8 lanes
- Adaptive EQ and de-emphasis with up to 30 dB loss compensation
- BOM integration and smaller package sizes save board cost and area
- Low-power modes scale with speed and drive strength
- High ease of use



#### **Timing Solutions**

- End-to-end offerings, including synthesis, rate conversion, attenuation, and distribution
- Ultra-low-jitter (160 fs) synthesizers and attenuators
- Ultra-low additive jitter, cost-efficient buffers
- Application specific with custom configuration— MiClockDesigner™
- Validated with the Agilent Time Domain PCI-SIG Compliance Software Suite

## PCIe Signal Integrity and Timing Solutions

### PCle Signal Integrity

Improve weak or degraded signals with Microsemi's PCle signal integrity solutions. With industry-exclusive EQNOX™ adaptive equalization, Microsemi's PCle redrivers and crosspoint switches deliver excellent performance in a compact footprint with flexible lane configurations for Gen1/2/3 applications, including passthrough buffer, non-blocking matrix switching, replication of inputs to multiple outputs, and multiplexing.



Product	Ports	Ports Max Rate Part Type		Receiver Type	Max Link Width
VSC3340-01	40 × 40	6.5G	Crosspoint Switch	CTLE	PCle 2.0 × 16
VSC3316	16 × 16	11.5G	Crosspoint Switch	CTLE	PCle 3.0 × 8
VSC3308	8 × 8	11.5G	Crosspoint Switch	CTLE	PCle 3.0 × 4
VSC7112	4, Dual 2 × 2	8.5G	Redriver with mux/demux	Adaptive CTLE	PCle 3.0 × 2

### Clock Synthesis

The miClockSynth™ family of high-performance, any-rate multiplier and frequency synthesizer devices simplifies board design by generating ultra-low-jitter clock signals from a single crystal or crystal oscillator while generating additional independent frequency families.



Product	Frequency Families	Outputs	Inputs	Jitter Performance RMS	Package (mm)
ZL3025x	1	Up to 3 diff/6SE 1 Hz-1035 MHz	10 M-1250 MHz	160 fs	5 × 5 QFN
ZL3026x	4	Up to 10 diff/20SE 1 Hz-1035 MHz	10 M-1250 MHz	170 fs	8 × 8 QFN

Gen 1-4 PCIe Clock Generators

Product	Independent Output Freq. Families	Inputs	Crystal Input Freq. Range	Xtal Oscillator or CMOS Input Freq. Range		Typical Jitter fs RMS	Default Output Configurations	Output Freq. Range	Host Bus	Supply Voltage	Pkg Size (mm)
ZL30281	1	1 XTAL	25 M	25 M	1	160	4	25 M, 100 M	SPI/I2C	3.3 + 1.8	5 x 5
ZL30282	2	2 XTAL	50 M	50 M	1	160	8	25 M, 75 M 100 M	SPI/I2C	See note	8 x 8

 $2.5\ V$  only,  $3.3\ V$  only,  $1.8\ V+2.5\ V$ ,  $1.8\ V+3.3\ V$ 

### Clock Fanout Buffers

Microsemi's high-performance buffers complement clock synthesis devices by providing additional fanout capabilities and minimal jitter combined with the industry's best power supply noise rejection performance. This preserves signal integrity by adding ultra-low jitter and filtering noise from power supplies, resulting in better performance while simplifying engineering board design efforts.



Product	Input Outputs		Output Frequency	Additive Jitter RMS	Package (mm)
ZL40xxx	1, 2, and XO, any signal type	2, 4, 6, 8 LVPECL or LVDS	750 MHz	<100 fs (as low as 39 fs)	3 × 3 and 5 × 5 QFN
ZL4024x, ZL4023x	2 inputs, XTAL, XO, any signal type	4, 5, 10 LVPECL, LVDS, HCSL, or LVCMOS	1.6 GHz	<50 fs (as low as 25 fs)	5 × 5 QFN
ZL3024x	3 inputs, XTAL, XO, any signal type	3, 6, or 10, any native signal diff or SE, configurable by output	1 GHz	<170 fs	8 × 8 QFN

## PCIe Fanout and Storage Switches

### PFX PCIe Fanout Switches

Microsemi Switchtec™ PFX fanout PCle switches provide the industry's highest-density, lowest-power PCle switch for data center, communications, workstation, and video production applications. With simple hardware configuration and advanced diagnostics and debug capabilities, the PFX enables PCle solutions for a wide variety of systems, from just a bunch of flash (JBOF) to general purpose applications requiring low-power and high-reliability PCle switching.



Product	Lanes	Description	Package Type
PM8531 PFX 24xG3	24	PFX 24xG3, 24-lane PCle Gen3 Fanout Switch	650-pin, 27 mm × 27 mm FCBGA package, 1 mm ball pitch
PM8532 PFX 32xG3	32	PFX 32xG3, 32-lane PCle Gen3 Fanout Switch	650-pin, 27 mm × 27 mm FCBGA package, 1 mm ball pitch
PM8533 PFX 48xG3	48	PFX 48xG3, 48-lane PCle Gen3 Fanout Switch	650-pin, 27 mm × 27 mm FCBGA package, 1 mm ball pitch
PM8534 PFX64xG3	64	PFX 64xG3, 64-lane PCle Gen3 Fanout Switch	1311-pin, 37.5 mm × 37.5 mm FCBGA package, 1 mm ball pitch
PM8535 PFX 80xG3	80	PFX 80xG3, 80-lane PCle Gen3 Fanout Switch	1311-pin, 37.5 mm × 37.5 mm FCBGA package, 1 mm ball pitch
PM8536 PFX 96xG3	96	PFX 96xG3, 96-lane PCIe Gen3 Fanout Switch	1311-pin, 37.5 mm × 37.5 mm FCBGA package, 1 mm ball pitch

### PFX-I Industrial Temperature Fanout Switches

Microsemi Switchtec<sup>TM</sup> PFX-I fanout PCle switches support the full feature set of the PFX switch with an extended industrial temperature operating\* range of -40 °C to 105 °C ( $T_a$  to  $T_j$ ). PFX-I switches also provide the industry's highest-density and lowest-power, with simple hardware configuration and advanced diagnostics and debug capabilities. Typical applications include data center equipment, defense, industrial servers, test equipment, cellular infrastructure, access networks, metro networks, and core networking.



Product	Lanes	Description	Package Type
PM8571 PFX-I 24xG3	24	PFX 24xG3, 24-lane PCle Gen3 Fanout Switch	650-pin, 27 mm × 27 mm FCBGA package, 1 mm ball pitch
PM8572 PFX-I 32xG3	32	PFX 32xG3, 32-lane PCle Gen3 Fanout Switch	650-pin, 27 mm × 27 mm FCBGA package, 1 mm ball pitch
PM8573 PFX-I 48xG3	48	PFX 48xG3, 48-lane PCle Gen3 Fanout Switch	650-pin, 27 mm × 27 mm FCBGA package, 1 mm ball pitch
PM8574 PFX-I 64xG3	64	PFX 64xG3, 64-lane PCle Gen3 Fanout Switch	1311-pin, 37.5 mm × 37.5 mm FCBGA package, 1 mm ball pitch
PM8575 PFX-I 80xG3	80	PFX 80xG3, 80-lane PCle Gen3 Fanout Switch	1311-pin, 37.5 mm × 37.5 mm FCBGA package, 1 mm ball pitch
PM8576 PFX-I 96xG3	96	PFX 96xG3, 96-lane PCIe Gen3 Fanout Switch	1311-pin, 37.5 mm × 37.5 mm FCBGA package, 1 mm ball pitch

Note: PFX TJunction: 0 °C to 105 °C. PFX-I T<sub>Ambient</sub>: 40 °C to T<sub>Junction</sub>: 105 °C. PFX-I doesn't support Adaptive Voltage Scaling (AVS).

#### PFX-L Fanout-Lite PCle Switches

Microsemi Switchtec PFX-L fanout-lite PCle switches support up to 96 lanes, 24 ports, x4/x8/x16 port bifurcation, two non-transparent bridges (NTBs), hot-plug controllers, advanced diagnostics and debug, end-to-end data integrity, SRIS, and low power. The PFX-L switches maintain footprint compatibility with the PFX switch family. Typical applications for the PFX-L include data center equipment, defense, industrial servers, workstations, test equipment, video production and broadcasting equipment, cellular infrastructure, access networks, metro networks, and core networking.



Product	Lanes	Description	Package Type
PM8561 PFX-L 24xG3	24	PFX-L 24xG3, 24-lane Fanout-Lite PCle Gen3 Switch	650-pin, 27 mm × 27 mm FCBGA package, 1 mm ball pitch
PM8562 PFX-L 32xG3	32	PFX-L 32xG3, 32-lane Fanout-Lite PCle Gen3 Switch	650-pin, 27 mm × 27 mm FCBGA package, 1 mm ball pitch
PM8563 PFX-L 48xG3	48	PFX-L 48xG3, 48-lane Fanout-Lite PCle Gen3 Switch	650-pin, 27 mm × 27 mm FCBGA package, 1 mm ball pitch
PM8564 PFX-L 64xG3	64	PFX-L 64xG3, 64-lane Fanout-Lite PCle Gen3 Switch	1311-pin, 37.5 mm × 37.5 mm FCBGA package, 1 mm ball pitch
PM8565 PFX-L 80xG3	80	PFX-L 80xG3, 80-lane Fanout-Lite PCle Gen3 Switch	1311-pin, 37.5 mm × 37.5 mm FCBGA package, 1 mm ball pitch
PM8566 PFX-L 96xG3	96	PFX-L 96xG3, 96-lane Fanout-Lite PCle Gen3 Switch	1311-pin, 37.5 mm × 37.5 mm FCBGA package, 1 mm ball pitch

## PCIe Fanout and Storage Switches

### PSX PCIe Storage Switches

Microsemi Switchtec PSX PCIe storage switches are engineered to scale PCIe flash in high-performance, robust storage systems, providing the industry's highest-density, lowest-power, high-reliability switch, and is also the first programmable PCIe switch with an integrated processor. Using the PSX Software Development Kit (SDK), customer can enhance PCIe switch functionality and customize error handling.



Product	Lanes	Description	Package Type
PM8541 PSX 24xG3	24	PSX 24xG3, 24-lane PCIe Gen3 Storage Switch	650-pin, 27 mm × 27 mm FCBGA package, 1 mm ball pitch
PM8542 PSX 32xG3	32	PSX 32xG3, 32-lane PCle Gen3 Storage Switch	650-pin, 27 mm × 27 mm FCBGA package, 1 mm ball pitch
PM8543 PSX 48xG3	48	PSX 48xG3, 48-lane PCIe Gen3 Storage Switch	650-pin, 27 mm × 27 mm FCBGA package, 1 mm ball pitch
PM8544 PSX 64xG3	64	PSX 64xG3, 64-lane PCIe Gen3 Storage Switch	1311-pin, 37.5 mm × 37.5 mm FCBGA package, 1 mm ball pitch
PM8545 PSX 80xG3	80	PSX 80xG3, 80-lane PCIe Gen3 Storage Switch	1311-pin, 37.5 mm × 37.5 mm FCBGA package, 1 mm ball pitch
PM8546 PSX 96xG3	96	PSX 96xG3, 96-lane PCle Gen3 Storage Switch	1311-pin, 37.5 mm × 37.5 mm FCBGA package, 1 mm ball pitch

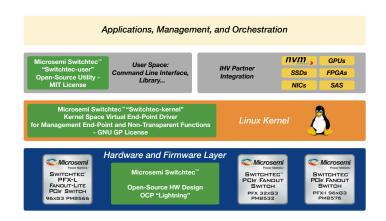
### Switchtec PAX Gen3 Advanced Fabric PCle Switch Family

The Microsemi Switchtec™ PAX Gen3 Advanced Fabric PCle Switch family comprises programmable and high-reliability PCle Gen3 switches supporting high performance PCle fabric connectivity, multi-host sharing of SR-IOV endpoints, up to 96 lanes, 48 ports, 24 virtual switch partitions, and hot- and surprise-plug controllers for each port. The switch family also features advanced error containment, comprehensive diagnostics and debug capabilities, a wide breadth of I/O interfaces, and an integrated MIPS processor. PAX switches utilize a system-on-chip architecture that optionally enables customer differentiated solutions through firmware customization and enhancements. Applications for the PAX family include scalable multi-host systems, SR-IOV enabled JBOFs, composable, disaggregated systems and rack scale architectures.



Product	Part Number	Lanes	Ports	Hot-Plug Controllers	Package
PAX 96xG3 PCle Gen3 Advanced Fabric Switch	PM8556B-FEIP	96	48	48	37.5 mm x 37.5 mm
PAX 80XG3 PCle Gen3 Advanced Fabric Switch	PM8555B-FEIP	80	40	40	37.5 mm x 37.5 mm
PAX 64xG3 PCle Gen3 Advanced Fabric Switch	PM8554B-FEIP	64	32	32	37.5 mm x 37.5 mm
PAX 48xG3 PCle Gen3 Advanced Fabric Swttch	PM8553B-F3EIP	48	24	24	27.0 mm x 27.0 mm
PAX 32xG3 PCle Gen3 Advanced Fabric Switch	PM8552B-F3EIP	32	16	16	27.0 mm x 27.0 mm
PAX 24xG3 PCle Gen3 Advanced Fabric Swttch	PM8551B-F3EIP	24	12	12	27.0 mm x 27.0 mm

Switchtec™ Open Source Linux Drivers, Hardware, Open Collaboration, and Technology Sharing



### FPGA and SoC PCIe Interface Solutions

### PolarFire PCI Express Features

Each PolarFire FPGA integrates two low-power built-in PCle Gen2 controllers, allowing seamless and easy connectivity to one or more host processors. Details are provided in <a href="PolarFire FPGA">PolarFire FPGA</a> documentation on our website. The following are PCle features:

- ×1, ×2, and ×4 lane support
- Suitable for root port, native endpoint
- PCI Express base specification revision 2.0 and 1.1 compliant
- AXI4 master and slave interfaces to the FPGA fabric
- Single function capability
- Advanced error reporting (AER) support
- Integrated clock domain crossing (CDC) to support user-selected AXI4 frequency
- Lane reversal support
- Legacy PCI power management support
- Native active state power management L0s and L1 state support
- Power management event (PME message)
- MSI and legacy INT message support
- Latency tolerance reporting (LTR)
- L1 PM sub-states with CLKREQ
- Address translation tables between the PCle and AXI4 domains

#### SmartFusion2 and IGI OO2 PCIe Features

The SmartFusion2 and IGLOO2 transceivers provide full support for PCI Express Gen 2.0. Details are provided in <u>SmartFusion2 Documents</u> and <u>IGLOO2 Documents</u> on our website. Features include:

- Gen1/Gen2 rates at x1, x2 and x4 links
- Endpoint Topology
- Single-Function/Single-VC
- Receiver and Transmit buffers support error correction and coding (ECC)
- Fabric Interface options of AXI3 Master/Slave or AHB32 Master/Slave
- Address translation window support between PCIe and local device address space

### PCI-SIG Compliance

Multiple solutions from Microsemi solutions have passed PCI-SIG compliance suites.

Please refer to the PCI-SIG integrators list to view Microsemi PCI Solutions.

### Why Choose Microsemi for PCle?

Microsemi keenly recognizes the importance of interoperability to address the design requirements of your PCIe network. Microsemi is actively involved in the advancement of PCIe standards, and ensures that all of our PCIe interfaced products properly conform to these standards. Microsemi also regularly participates in PCI-SIG compliance workshop events, proving interoperability of our Flashtec, Switchtec, Tachyon®, and Microsemi Adaptec® products. A list of our PCI Express 3.0-compliant products can be found on the PCI-SIG integrators list.

Microsemi's turnkey PCIe reference designs and field-proven interoperable solutions portfolio will streamline your design, accelerating your time to market with differentiated products. Contact your local Microsemi sales office today to find the right PCIe technologies and products for your design needs.





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